Solderless Breadboard





Specifications

Housing Material : ABS Plastic
Spring Clips : Copper, Ni plated
Wire Range : Sol 29AWG to 20AWG

Rated Voltage : 300V
Rated Current : 3A to 5A
4 Terminal Strip : 2,520 Tie-point
7 Distribution Strip : 700 Tie-point

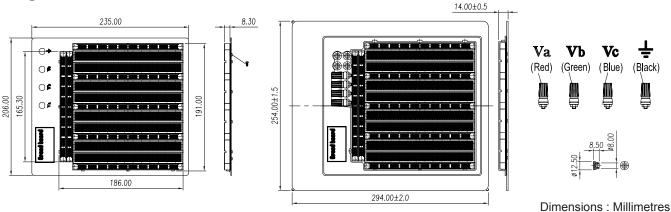
4 Binding posts

Black Metal Plate : 207mm × 235mm × 1mm

Pitch : 2.54mm

Dimensions : 186mm × 191mm × 8.3mm

Diagram



Linear Dimension (Tolerance Standard GB/T 14486-2008)											=	_		//	\perp	
Variable Range	to 6	Over 6 to 10	Over 10 to 18	Over 18 to 30	Over 30 to 50	Over 50 to 80	Over 80 to 120	Over 120 to 160	Over 160 to 200	Over 200 to 250	Over 250 to	all	to 5	Over 5 to 30	Over 30 to 120	Over 120 to
Tolerance	±0.1	±0.14	±0.19	±0.25	±0.32	±0.43	±0.57	±0.72	±0.88	±1.05	±1.25	0.5	0.025	0.06	0.12	0.4

Part Number Table

Description	Part Number				
Solderless Breadboard	MCBB3060				

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